

STARPOWER

SEMICONDUCTOR

IGBT

GD450MMS65L6S

650V/450A 3-level in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as 3-level-application.

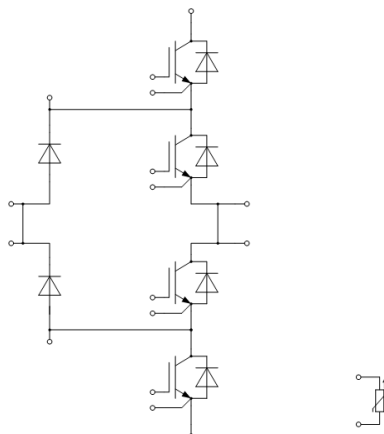
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175 °C
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology
- Qualified for industrial applications according to the relevant tests of IEC 60747,60749 and 60068

Typical Applications

- Solar power
- 3-level-application

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**T1,T4 IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_{CN}	Implemented Collector Current	450	A
I_C	Collector Current @ $T_C=75^{\circ}\text{C}$	370	A
I_{CRM}	Repetitive Peak Collector Current tp limited by T_{vjop}	900	A
P_D	Maximum Power Dissipation @ $T_{vj}=175^{\circ}\text{C}$	1136	W

T2,T3 IGBT

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_{CN}	Implemented Collector Current	450	A
I_C	Collector Current @ $T_C=75^{\circ}\text{C}$	370	A
I_{CRM}	Repetitive Peak Collector Current tp limited by T_{vjop}	900	A
P_D	Maximum Power Dissipation @ $T_{vj}=175^{\circ}\text{C}$	1136	W

D1-D4 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	650	V
I_{FN}	Implemented Forward Current	400	A
I_F	Diode Continuous Forward Current @ $T_C=75^{\circ}\text{C}$	305	A
I_{FRM}	Repetitive Peak Forward Current tp limited by T_{vjop}	800	A

D5,D6 Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	650	V
I_{FN}	Implemented Forward Current	400	A
I_F	Diode Continuous Forward Current @ $T_C=75^{\circ}\text{C}$	269	A
I_{FRM}	Repetitive Peak Forward Current tp limited by T_{vjop}	800	A

Module

Symbol	Description	Value	Unit
T_{vjmax}	Maximum Junction Temperature	175	$^{\circ}\text{C}$
T_{vjop}	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	3200	V
d_{Creep}	Terminal to Heatsink	>11	mm
d_{Clear}	Terminal to Heatsink	>9	mm
RTI	RTI Elec, housing	130	$^{\circ}\text{C}$

T1,T4 IGBT Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=450\text{A}, V_{GE}=15\text{V}, T_{vj}=25^{\circ}\text{C}$		1.45	1.90	V
		$I_C=450\text{A}, V_{GE}=15\text{V}, T_{vj}=125^{\circ}\text{C}$		1.60		
		$I_C=450\text{A}, V_{GE}=15\text{V}, T_{vj}=150^{\circ}\text{C}$		1.65		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=7.20\text{mA}, V_{CE}=V_{GE}, T_{vj}=25^{\circ}\text{C}$	4.4	5.0	5.6	V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			1.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			400	nA
R_{Gint}	Internal Gate Resistance			0.8		Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=100\text{kHz}, V_{GE}=0\text{V}$		30.3		nF
C_{oes}	Onput Capacitance			1.33		nF
C_{res}	Reverse Transfer Capacitance			0.49		nF
Q_G	Gate Charge	$V_{GE}=-15\dots+15\text{V}$		2.77		μC
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=470\text{V}, I_C=230\text{A}, R_{Gon}=2.2\Omega, R_{Goff}=4.7\Omega, L_S=24\text{nH}, V_{GE}=-8\text{V}/+15\text{V}, T_{vj}=25^{\circ}\text{C}$		79		ns
t_r	Rise Time			28		ns
$t_{d(off)}$	Turn-Off Delay Time			624		ns
t_f	Fall Time			34		ns
E_{on}	Turn-On Switching Loss			4.83		mJ
E_{off}	Turn-Off Switching Loss			3.63		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=470\text{V}, I_C=230\text{A}, R_{Gon}=2.2\Omega, R_{Goff}=4.7\Omega, L_S=24\text{nH}, V_{GE}=-8\text{V}/+15\text{V}, T_{vj}=125^{\circ}\text{C}$		81		ns
t_r	Rise Time			28		ns
$t_{d(off)}$	Turn-Off Delay Time			653		ns
t_f	Fall Time			30		ns
E_{on}	Turn-On Switching Loss			7.39		mJ
E_{off}	Turn-Off Switching Loss			3.98		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=470\text{V}, I_C=230\text{A}, R_{Gon}=2.2\Omega, R_{Goff}=4.7\Omega, L_S=24\text{nH}, V_{GE}=-8\text{V}/+15\text{V}, T_{vj}=150^{\circ}\text{C}$		79		ns
t_r	Rise Time			28		ns
$t_{d(off)}$	Turn-Off Delay Time			665		ns
t_f	Fall Time			32		ns
E_{on}	Turn-On Switching Loss			7.84		mJ
E_{off}	Turn-Off Switching Loss			4.09		mJ

T2,T3 IGBT Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=450\text{A}, V_{GE}=15\text{V}, T_{vj}=25^{\circ}\text{C}$		1.45	1.90	V
		$I_C=450\text{A}, V_{GE}=15\text{V}, T_{vj}=125^{\circ}\text{C}$		1.60		
		$I_C=450\text{A}, V_{GE}=15\text{V}, T_{vj}=150^{\circ}\text{C}$		1.65		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=7.20\text{mA}, V_{CE}=V_{GE}, T_{vj}=25^{\circ}\text{C}$	4.4	5.0	5.6	V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			1.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_{vj}=25^{\circ}\text{C}$			400	nA
R_{Gint}	Internal Gate Resistance			0.8		Ω
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}, f=100\text{kHz}, V_{GE}=0\text{V}$		30.3		nF
C_{oes}	Onput Capacitance			1.33		nF
C_{res}	Reverse Transfer Capacitance			0.49		nF
Q_G	Gate Charge	$V_{GE}=-15\dots+15\text{V}$		2.77		μC
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=470\text{V}, I_C=230\text{A}, R_{Gon}=2.2\Omega, R_{Goff}=15\Omega, L_S=28\text{nH}, V_{GE}=-8\text{V}/+15\text{V}, T_{vj}=25^{\circ}\text{C}$		68		ns
t_r	Rise Time			38		ns
$t_{d(off)}$	Turn-Off Delay Time			1428		ns
t_f	Fall Time			278		ns
E_{on}	Turn-On Switching Loss			4.82		mJ
E_{off}	Turn-Off Switching Loss			15.4		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=470\text{V}, I_C=230\text{A}, R_{Gon}=2.2\Omega, R_{Goff}=15\Omega, L_S=28\text{nH}, V_{GE}=-8\text{V}/+15\text{V}, T_{vj}=125^{\circ}\text{C}$		71		ns
t_r	Rise Time			38		ns
$t_{d(off)}$	Turn-Off Delay Time			1532		ns
t_f	Fall Time			304		ns
E_{on}	Turn-On Switching Loss			5.85		mJ
E_{off}	Turn-Off Switching Loss			17.1		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=470\text{V}, I_C=230\text{A}, R_{Gon}=2.2\Omega, R_{Goff}=15\Omega, L_S=28\text{nH}, V_{GE}=-8\text{V}/+15\text{V}, T_{vj}=150^{\circ}\text{C}$		71		ns
t_r	Rise Time			40		ns
$t_{d(off)}$	Turn-Off Delay Time			1556		ns
t_f	Fall Time			252		ns
E_{on}	Turn-On Switching Loss			5.95		mJ
E_{off}	Turn-Off Switching Loss			15.0		mJ

D1-D4 Diode Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=25^{\circ}\text{C}$		1.60	2.05	V
		$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=125^{\circ}\text{C}$		1.65		
		$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=150^{\circ}\text{C}$		1.65		
Q_r	Recovered Charge	$V_R=470\text{V}, I_F=230\text{A},$ $-di/dt=3350\text{A}/\mu\text{s}, L_S=28\text{nH},$ $V_{GE}=-8\text{V}, T_{vj}=25^{\circ}\text{C}$		15.0		μC
I_{RM}	Peak Reverse Recovery Current			282		A
E_{rec}	Reverse Recovery Energy			4.83		mJ
Q_r	Recovered Charge	$V_R=470\text{V}, I_F=230\text{A},$ $-di/dt=3290\text{A}/\mu\text{s}, L_S=28\text{nH},$ $V_{GE}=-8\text{V}, T_{vj}=125^{\circ}\text{C}$		24.9		μC
I_{RM}	Peak Reverse Recovery Current			351		A
E_{rec}	Reverse Recovery Energy			8.49		mJ
Q_r	Recovered Charge	$V_R=470\text{V}, I_F=230\text{A},$ $-di/dt=3160\text{A}/\mu\text{s}, L_S=28\text{nH},$ $V_{GE}=-8\text{V}, T_{vj}=150^{\circ}\text{C}$		27.2		μC
I_{RM}	Peak Reverse Recovery Current			361		A
E_{rec}	Reverse Recovery Energy			9.23		mJ

D5,D6 Diode Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=25^{\circ}\text{C}$		1.60	2.05	V
		$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=125^{\circ}\text{C}$		1.65		
		$I_F=400\text{A}, V_{GE}=0\text{V}, T_J=150^{\circ}\text{C}$		1.65		
Q_r	Recovered Charge	$V_R=470\text{V}, I_F=230\text{A},$ $-di/dt=9350\text{A}/\mu\text{s}, L_S=24\text{nH},$ $V_{GE}=-8\text{V}, T_{vj}=25^{\circ}\text{C}$		21.8		μC
I_{RM}	Peak Reverse Recovery Current			307		A
E_{rec}	Reverse Recovery Energy			7.11		mJ
Q_r	Recovered Charge	$V_R=470\text{V}, I_F=230\text{A},$ $-di/dt=9910\text{A}/\mu\text{s}, L_S=24\text{nH},$ $V_{GE}=-8\text{V}, T_{vj}=125^{\circ}\text{C}$		27.6		μC
I_{RM}	Peak Reverse Recovery Current			358		A
E_{rec}	Reverse Recovery Energy			8.60		mJ
Q_r	Recovered Charge	$V_R=470\text{V}, I_F=230\text{A},$ $-di/dt=9770\text{A}/\mu\text{s}, L_S=24\text{nH},$ $V_{GE}=-8\text{V}, T_{vj}=150^{\circ}\text{C}$		30.5		μC
I_{RM}	Peak Reverse Recovery Current			381		A
E_{rec}	Reverse Recovery Energy			9.57		mJ

NTC Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		k Ω
$\Delta R/R$	Deviation of R_{100}	$T_C=100^{\circ}\text{C}, R_{100}=493.3\Omega$	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K
$B_{25/80}$	B-value	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15\text{K}))]$		3411		K
$B_{25/100}$	B-value	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15\text{K}))]$		3433		K

Module Characteristics $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		15		nH
R_{thJC}	Junction-to-Case (per T1,T4 IGBT)			0.132	K/W
	Junction-to-Case (per T2,T3 IGBT)			0.132	
	Junction-to-Case (per D1-D4 Diode)			0.169	
	Junction-to-Case (per D5,D6 Diode)			0.196	
R_{thCH}	Case-to-Heatsink (per T1,T4 IGBT)		0.056		K/W
	Case-to-Heatsink (per T2,T3 IGBT)		0.056		
	Case-to-Heatsink (per D1-D4 Diode)		0.054		
	Case-to-Heatsink (per D5,D6 Diode)		0.066		
M	Mounting Torque, Screw:M5	3.0		5.0	N.m
G	Weight of Module		250		g

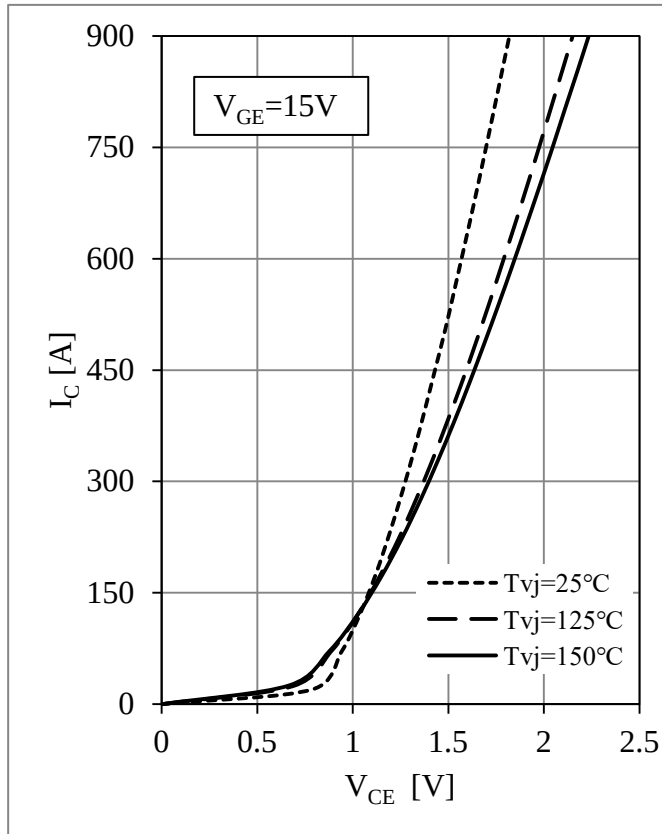


Fig 1. T1/T4 IGBT Output Characteristics

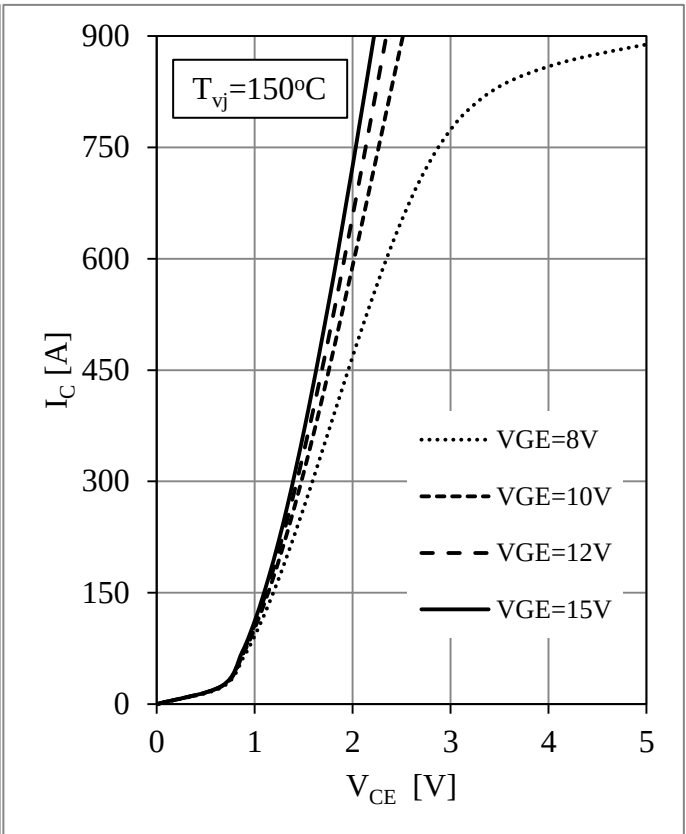


Fig 2. T1/T4 IGBT Output Characteristics

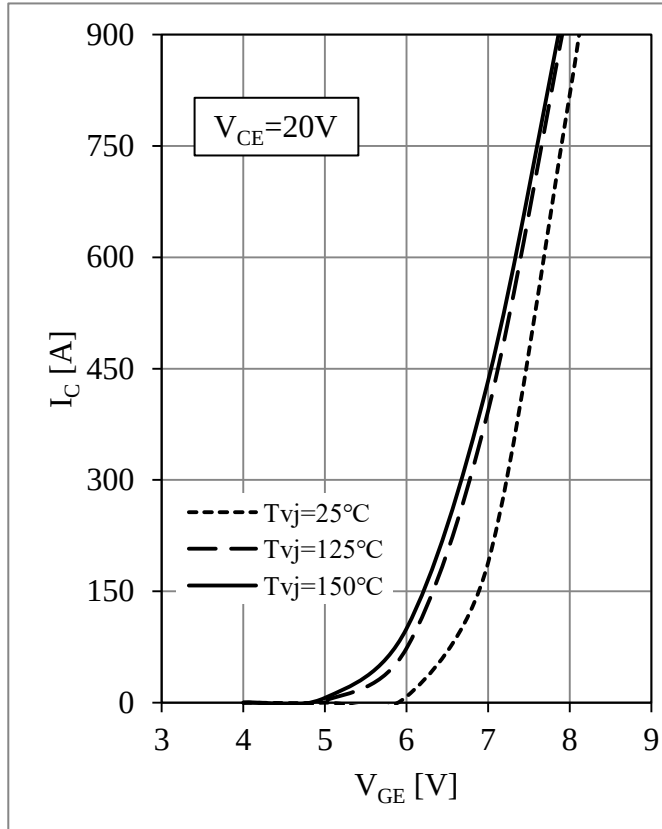
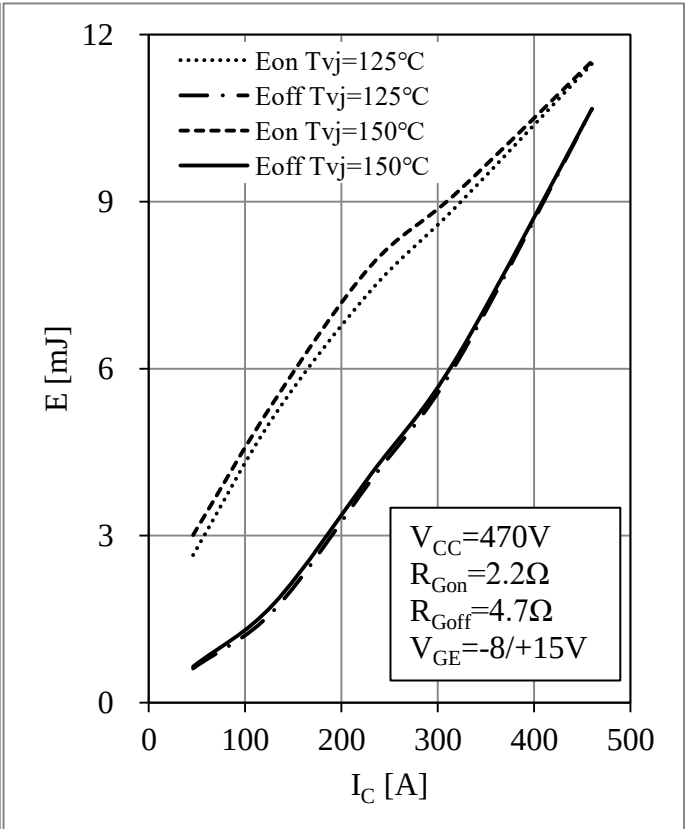
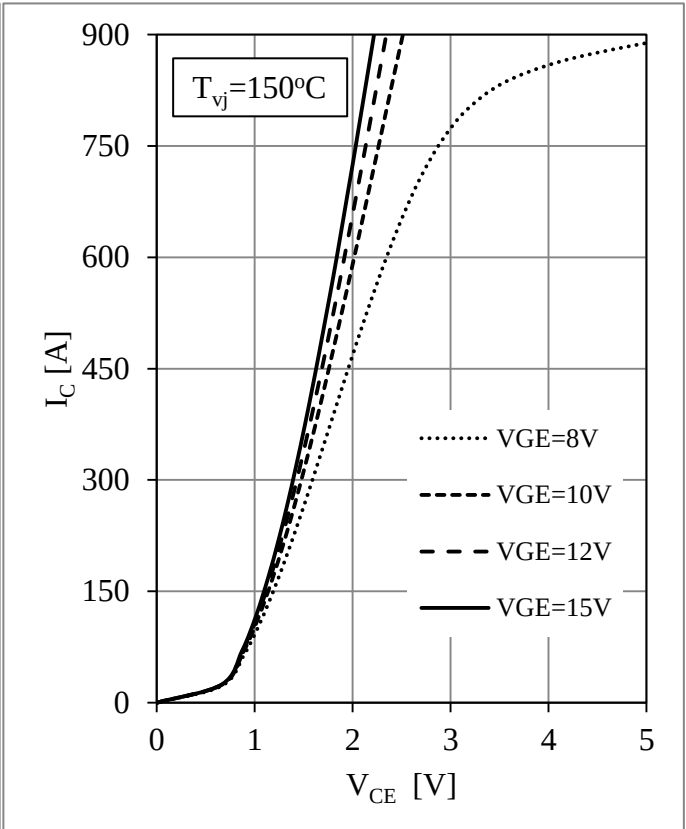
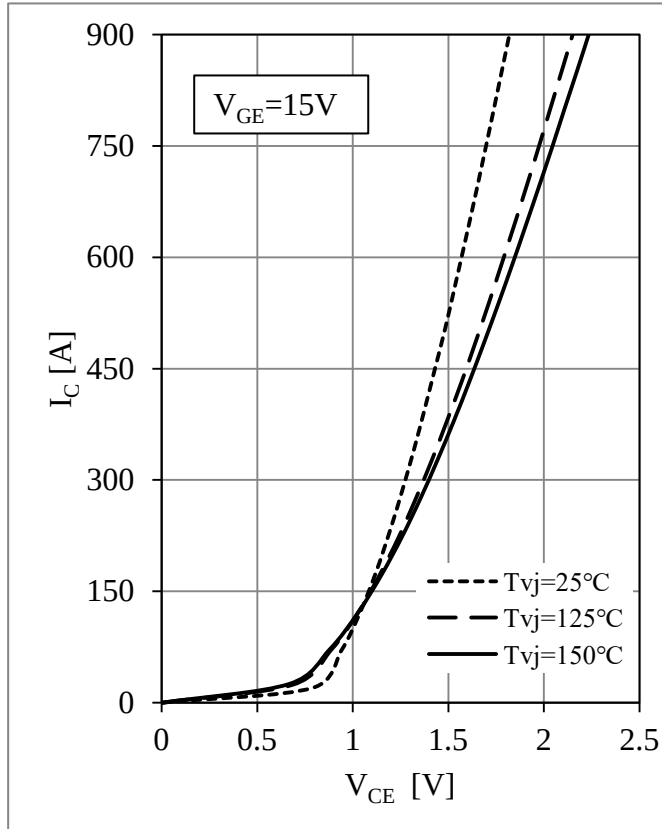
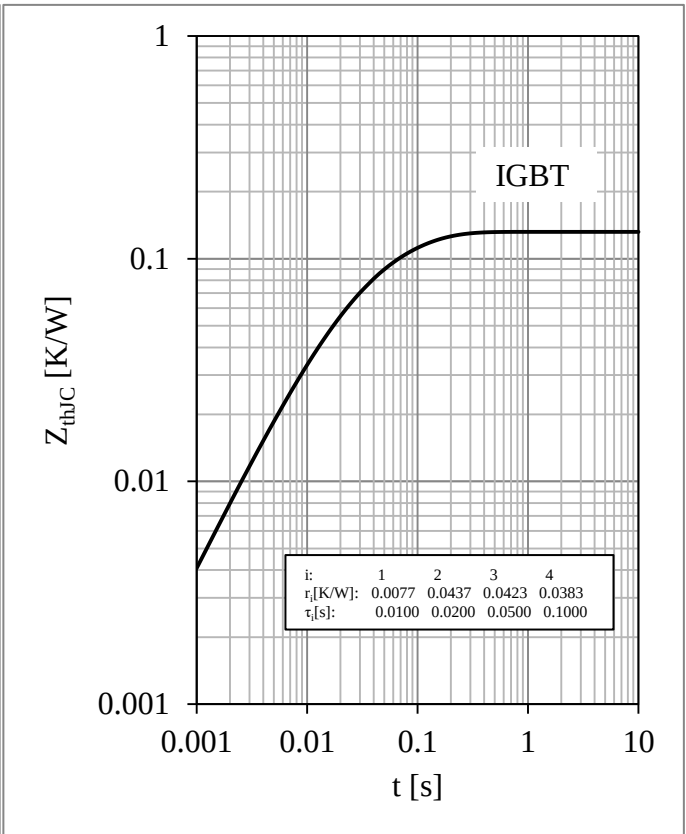
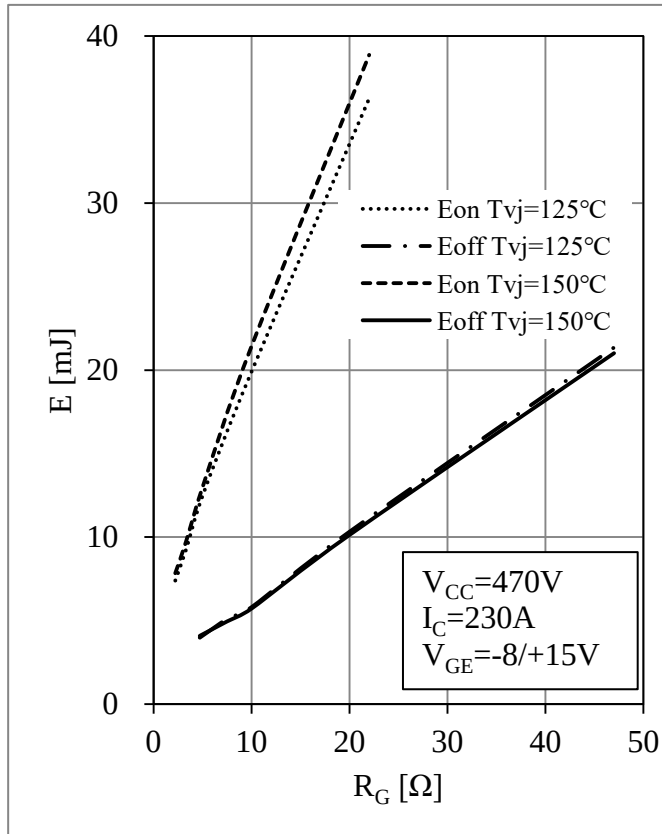


Fig 3. T1/T4 IGBT Transfer Characteristics

Fig 4. T1/T4 IGBT Switching Loss vs. I_C



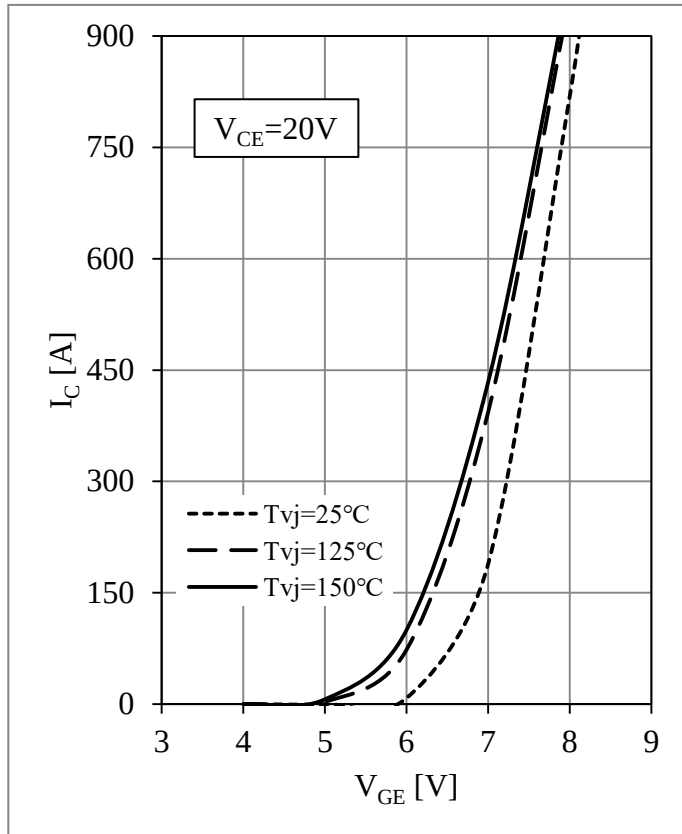


Fig 9. T2/T3 IGBT Transfer Characteristics

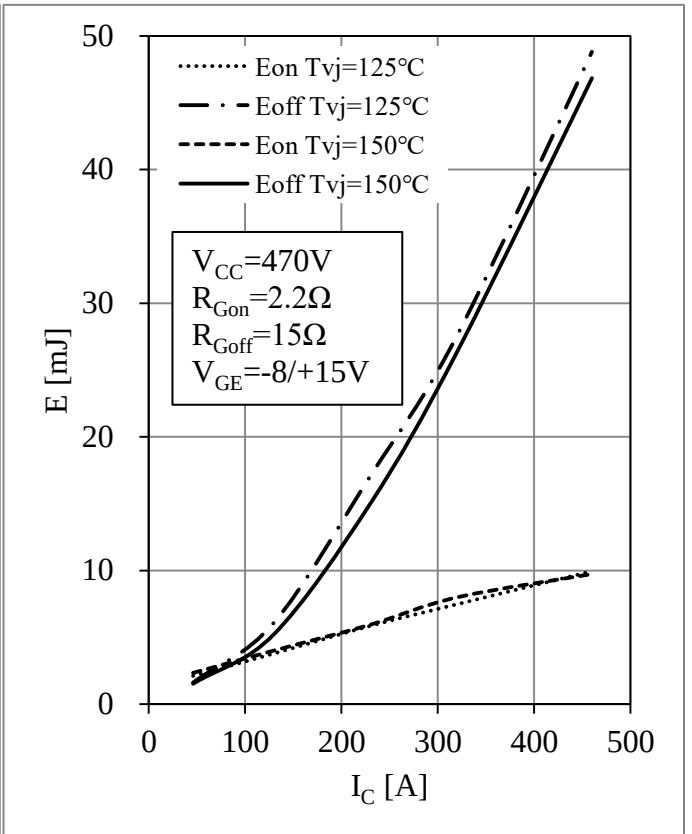
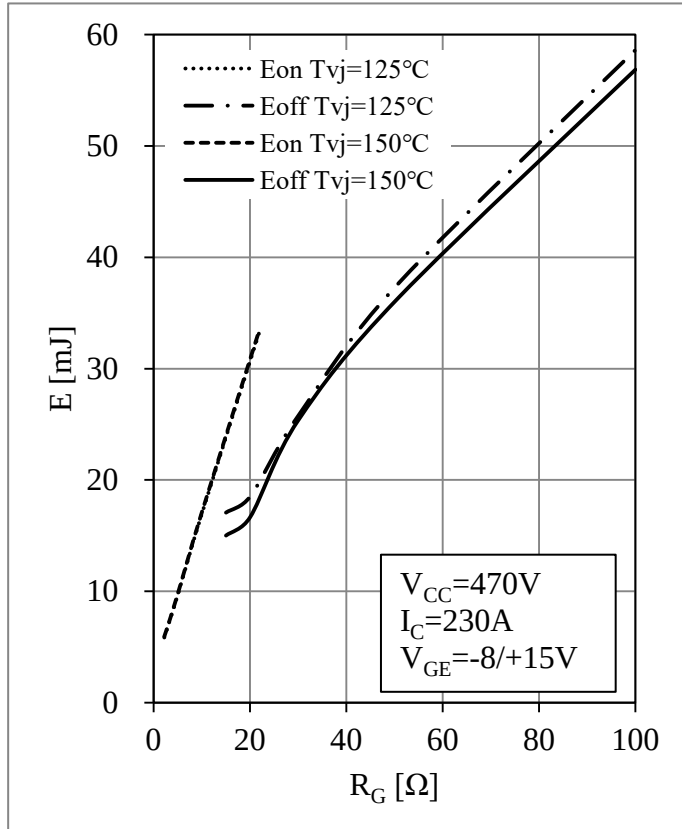
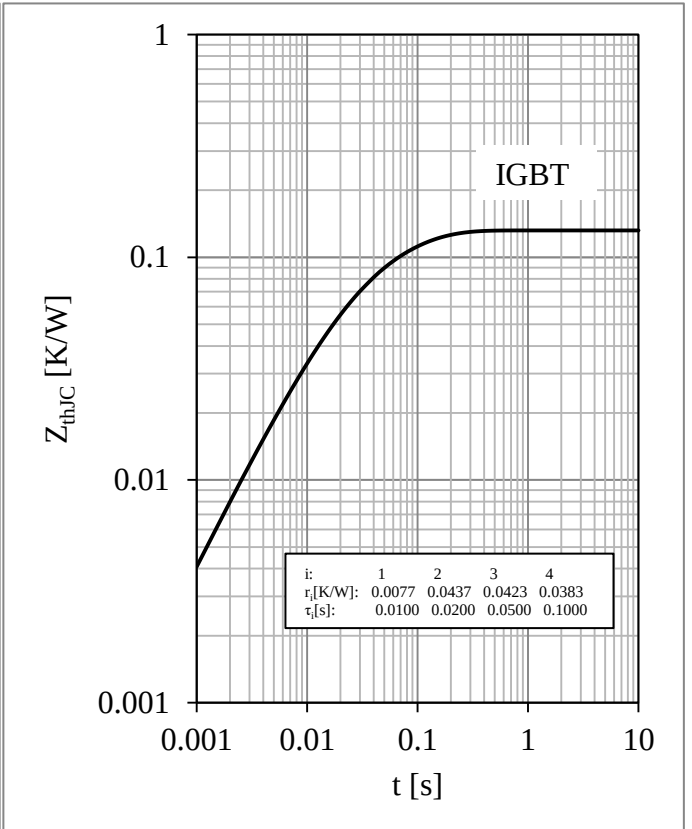
Fig 10. T2/T3 IGBT Switching Loss vs. I_C Fig 11. T2/T3 IGBT Switching Loss vs. R_G 

Fig 12. T2/T3 IGBT Transient Thermal Impedance

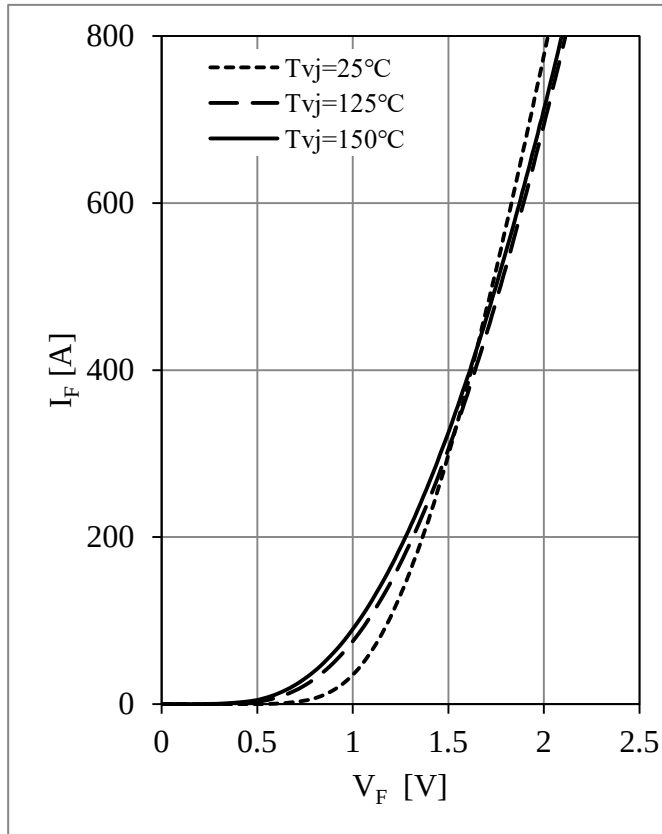


Fig 13. D1-D4 Diode Forward Characteristics

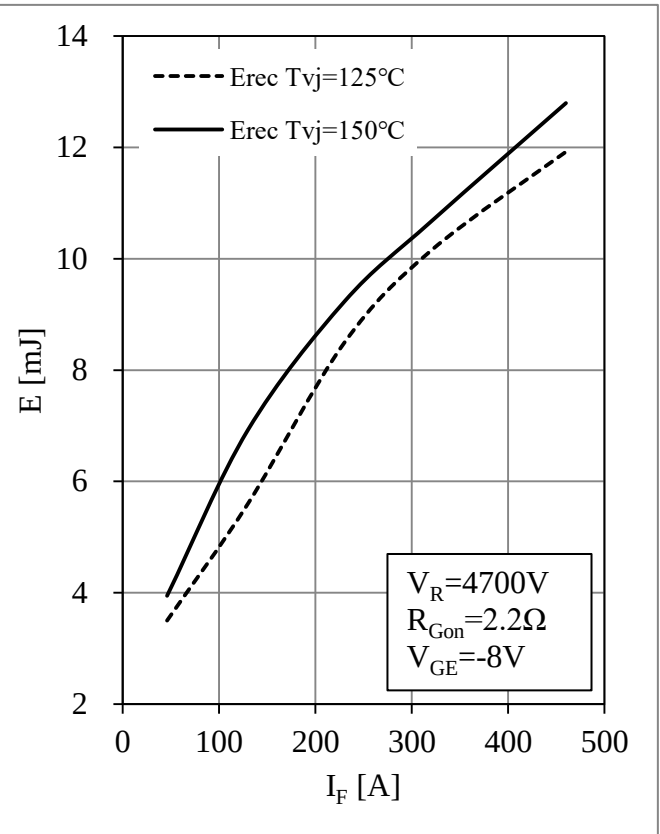
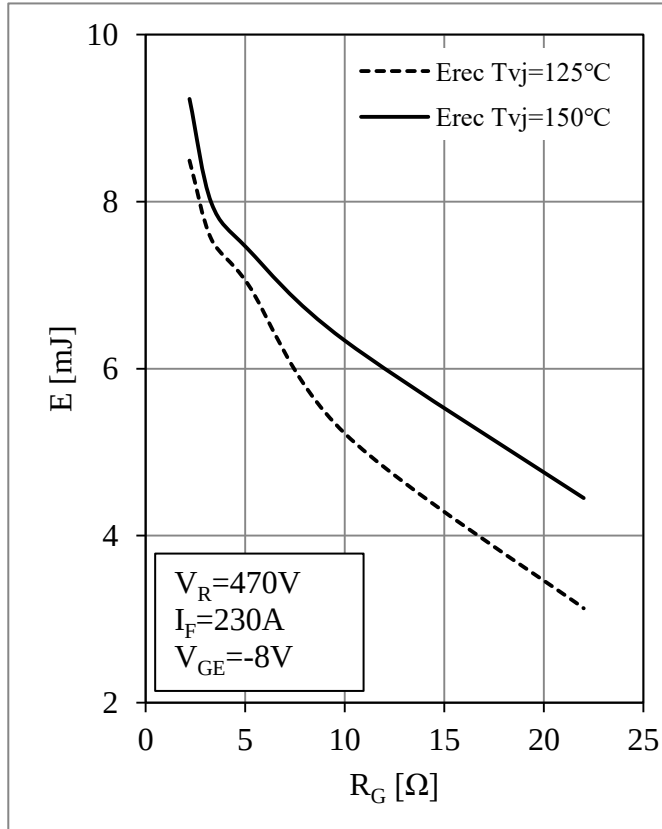
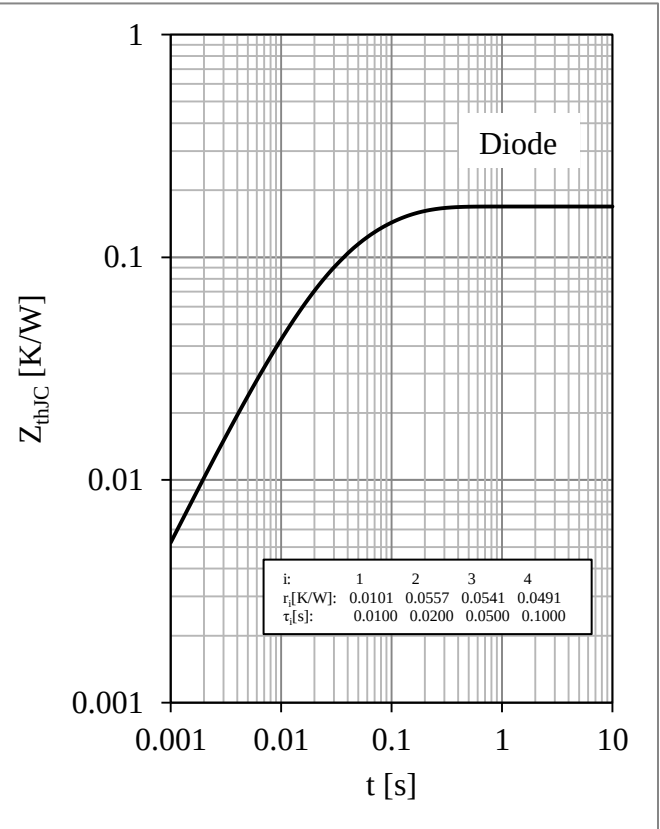
Fig 14. D1-D4 Diode Switching Loss vs. I_F Fig 15. D1-D4 Diode Switching Loss vs. R_G 

Fig 16. D1-D4 Diode Transient Thermal Impedance

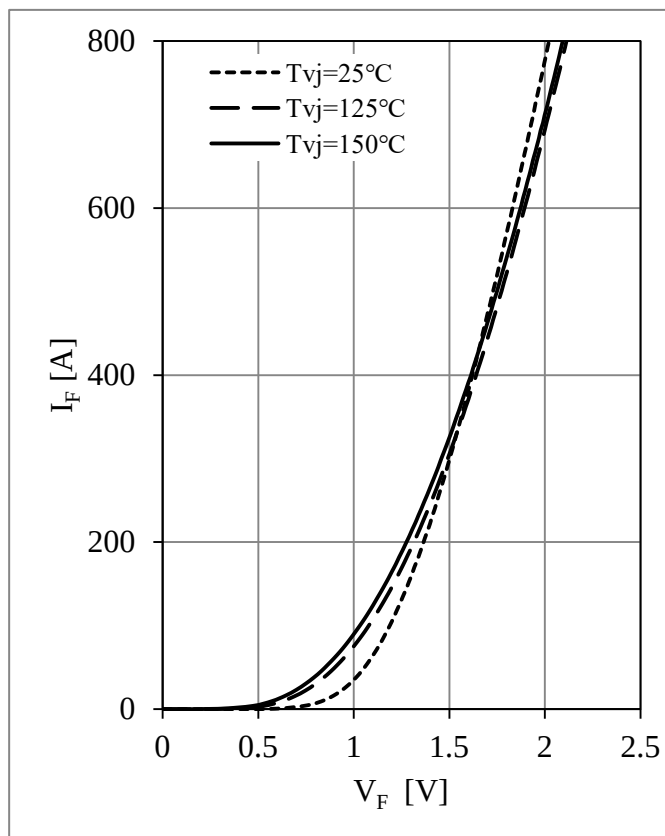


Fig 17. D5,D6 Diode Forward Characteristics

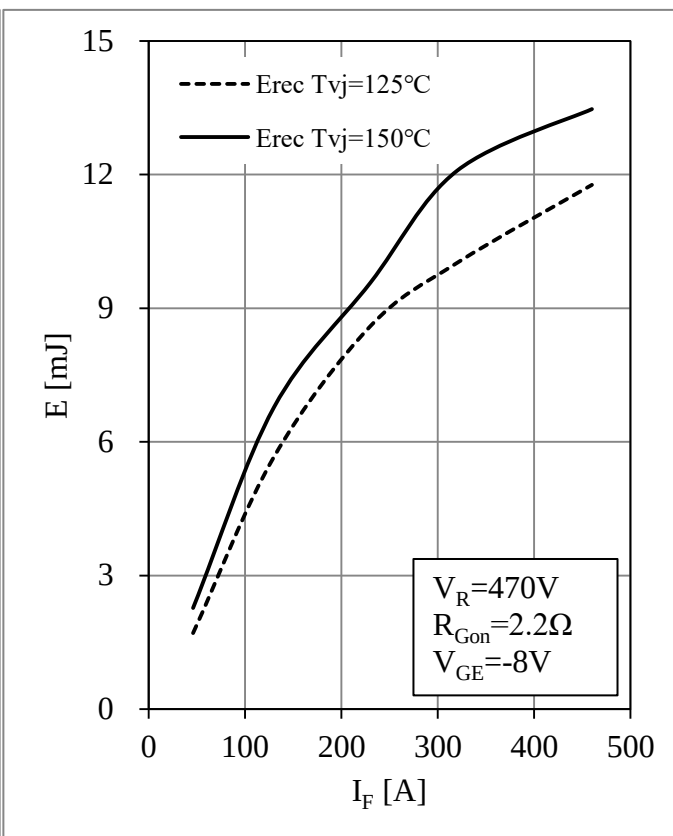
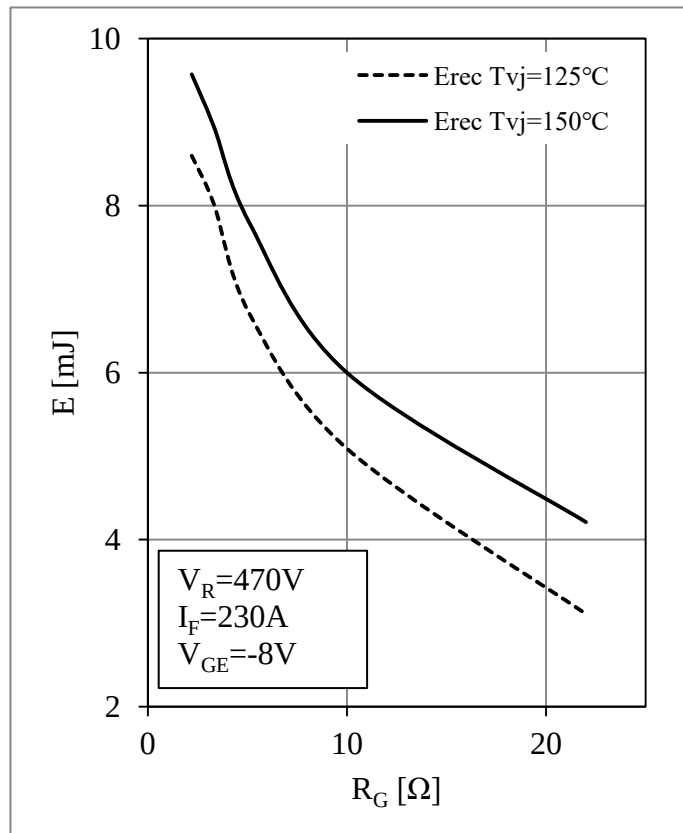
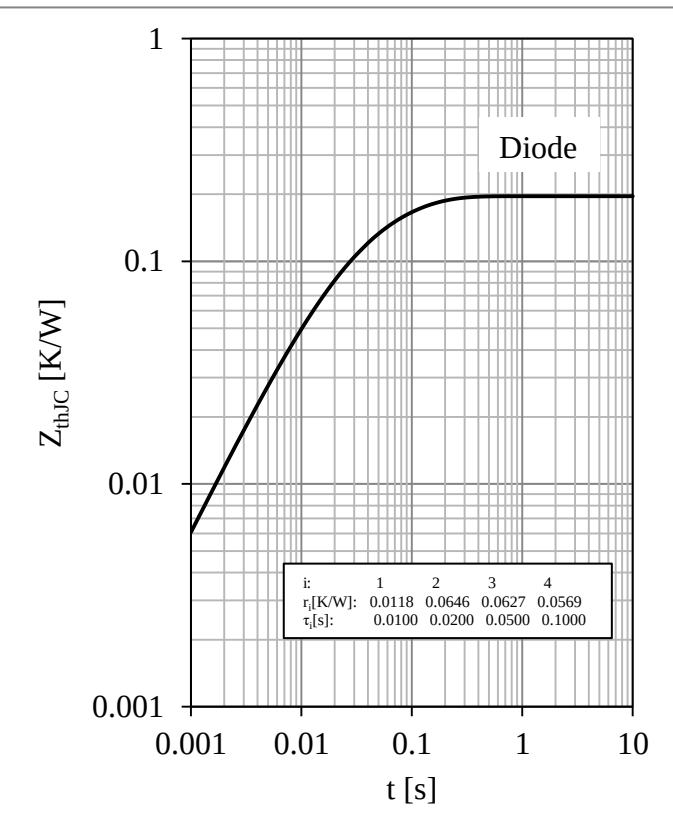
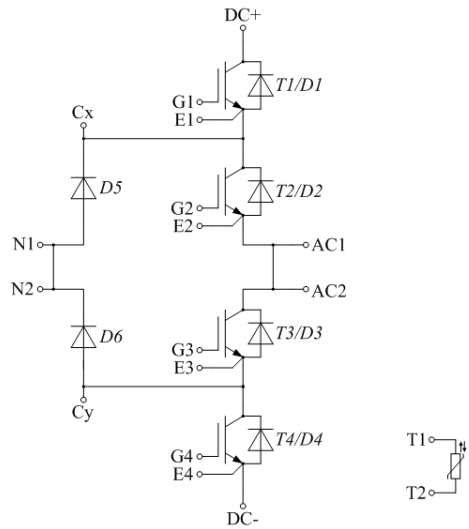
Fig 18. D5,D6 Diode Switching Loss vs. I_F Fig 19. D5,D6 Diode Switching Loss vs. R_G 

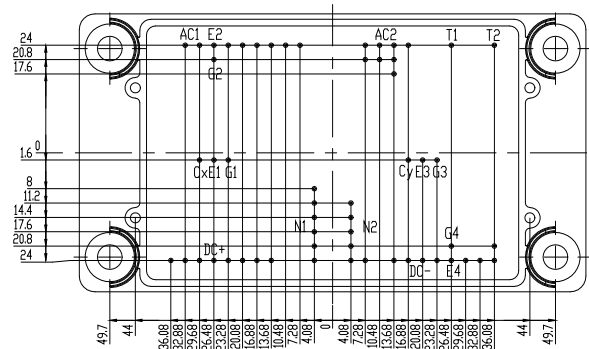
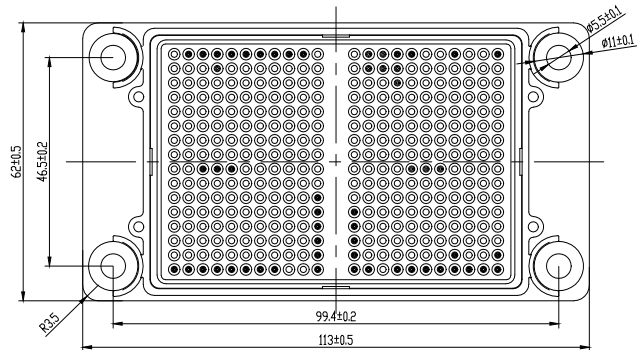
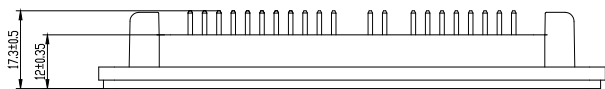
Fig 20. D5,D6 Diode Transient Thermal Impedance

Circuit Schematic



Package Dimensions

Dimensions in Millimeters



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